



Eighth-Brick Isolated DC/DC Converter

Features

- Wide input voltage range: 18 72Vin
- Output: 3.3V at 20A, 66W max.
- High Efficiency 90% Typical @ FL
- RoHS 3 Directive 2015/863/EU
- No minimum load/capacitance required
- Low height 0.406" (10.3mm) max.
- Baseplate Optional 0.500" (12.7mm) tall
- 2250V Isolation
- Withstands 100 V input transients
- Fixed-frequency operation
- Industry standard 1/8th brick footprint
- Full protection (OTP, OCP, OVP, UVLO auto-restart)
- Remote ON/OFF positive or negative enable logic options
- Remote sense
- Output voltage trim range: ±10% (industry-standard trim equations)
- Weight: 0.79 oz (22.4 g) open frame, 1.38 oz (39.1 g) baseplate model
- On-board input differential LC-filter
- Meets UL94, V-0 flammability rating
- Compliant to REACH (EC) No 1907/2006, 224 SVHC update
- Certified to UL/CSA60950-1, TUV per IEC/EN60950-1, 2nd edition
- Designed to meet Class B conducted emissions per FCC and EN55032 when used with external filter (see EMC Compliance section below.)

Description

The CPE20F36 "Cool Power Technologies" DC-DC converter is an open frame eighth-brick DC-DC converter that conforms to industry standard specifications. The converter operates over an input voltage range of 18 to 72 VDC, and provides a tightly regulated output voltage with an output current rating of 20 A. The output is fully isolated from the input and the converter meets Basic Insulation requirements. The standard feature set includes remote On/Off (positive or negative enable), input undervoltage lockout, output overvoltage protection, overcurrent and short circuit protections, output voltage trim, remote sense and overtemperature shutdown with hysteresis. The high efficiency of the CPE20F36 allows operation over a wide ambient temperature range with minimal derating (see Characteristic Curves section below.)



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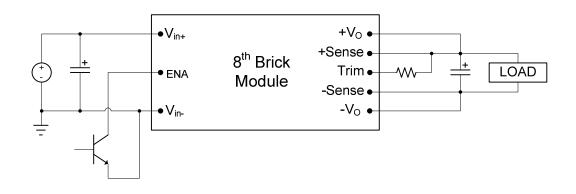




TABLE OF CONTENTS

SECTION	PAGE
FEATURES & DESCRIPTION	1
APPLICATION DIAGRAM	2
ELECTRICAL SPECIFICATIONS	3
CHARACTERISTIC PERFORMANCE CURVES	6
CHARACTERISTIC WAVEFORMS	7
APPLICATION NOTES	8
RIPPLE MEASUREMENTS TEST SET-UP	8
OUTPUT VOLTAGE TRIM EQUATIONS	9
THERMAL DERATING	10
EMC COMPLIANCE	12
MECHANICAL OUTLINE & PCB FOOTPRINT	13
ORDERING INFORMATION	15

APPLICATION DIAGRAM





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ELECTRICAL SPECIFICATIONS

18-72Vin, 3V3/20Aout

Conditions: $T_A = 25$ °C, Airflow = 300 LFM, Vin = 48 VDC, Cin = 100 μ F, unless otherwise specified.

Input Characteristics						
Parameter	Conditions	Min	Тур	Max	Unit	
Operating Input Voltage Range		18	48	72	VDC	
Input Under-Voltage Lock-out Turn-on Threshold Turn-off Threshold		17.2 15.8	17.6 16.2	18.0 16.6	VDC	
Input Voltage Transient	100ms			100	VDC	
Maximum Input Current	V _{IN} = 18VDC; I _{out} = 20A			4.3	Α	
Input Standby Current	Converter Disabled		2	5	mA	
Input No-Load Current	Converter Enabled		55	95	mA	
Short Circuit Input Current	RMS		30		mA	
Input Reflected Ripple Current	5Hz to 50MHz See Fig 13 for setup		15	25	mА _{РК-РК}	
Input Voltage Ripple Rejection	120Hz		50		dB	
Inrush Current	All	-	-	0.1	A²/s	
Output Characteristics						
Parameter	Conditions	Min	Тур	Max	Unit	
Output Voltage Set point	Sense pins connected to output pins	3.25	3.3	3.35	VDC	
Output Current				20	Α	
Output Current Limit Inception		21	24	30	Α	
Peak Short-Circuit Current	10mΩ Short			38	Α	
RMS Short-Circuit Current	10mΩ Short			3.5	A _{RMS}	
External Load Capacitance		0		10000	uF	
Output Ripple and Noise	20MHz Bandwidth 1 uF Ceramic + 22 uF Ceramic See Fig 14 for setup		20	60	mV _{PK-PK}	
Output Regulation Line: Load: Overall Output Regulation:	Over line, load & temp.	3.2	±1 ±1	±5 ±5 3.4	mV mV V	



Technical Datasheet

CPE20F36

ELECTRICAL SPECIFICATIONS (continued)

18-72Vin, 3V3/20Aout

Conditions: $T_A = 25$ °C, Airflow = 300 LFM, Vin = 48 VDC, Cin = 100 μ F, unless otherwise specified.

Efficiency					
Parameter	Conditions	Min	Тур	Max	Unit
Full Load	Vin = 24Vin	Vin = 24Vin 89.5			%
Full Load	Vin = 48Vin 89		90		%
F0%/ Land	Vin = 24Vin	89.5	91		%
50% Load	Vin = 48Vin 88.5		90		%
Dynamic Response					
Parameter	Conditions	Min	Тур	Max	Unit
Load Change 50%-75% or 25% to 50% of lout Max, di/dt = 0.1 A/µs	Co = 1 µF ceramic + 22 µF ceramic		100	150	mV
Settling Time to 1% of Vout			50		μs
Load Change 50%-75% or 25% to 50% of lout Max, di/dt = 0.2 A/µs	Co = 100 µF ceramic		100	180	mV
Settling Time to 1% of Vout	+ 330 µF Tantalum		100		μs
Isolation Specifications					
Isolation Capacitance			1000		pF
Isolation Resistance		10			ΜΩ
	Input to Output - Open Frame	2250			
Isolation Voltage	Input to Output - Baseplate	1500			V _{DC}
	Input to baseplate	750			V_{DC}
	Output to baseplate 750				V _{DC}
Reliability					
Per Telcordia SR-332, Issue 2:	MTFB	3,125,002		Hours	
Method I, Case 3 (I_0 =80% of I_0 _max, T_A =40°C, airflow = 200 lfm, 90% confidence)	FITs (failures in 10 ⁹ hours)	320			/10 ⁹ Hours





ELECTRICAL SPECIFICATIONS (continued)

18–72Vin, 3V3/20Aout

Conditions: Ta = 25 °C, Airflow = 300 LFM, Vin = 48 VDC, Cin=100 µF, unless otherwise specified.

Absolute Maximum Ratings						
Parameter	Conditions	Min	Тур	Max	Unit	
Input Voltage	Continuous Operation	0		75	VDC	
Operating Ambient Temperature		-40		+85	°C	
Storage Temperature		-55		+125	°C	
Feature Characteristics						
Parameter	Conditions	Min	Тур	Мах	Unit	
Switching Frequency			410		kHz	
Output Voltage Trim Range*		-10		+10	%	
Remote Sense Compensation*				+10	%	
Output Over-voltage Protection	Non-latching	115	120	130	%	
Over-temperature Protection	Avg. PCB temp, non-latching		135		°C	
Peak Backdrive Output Current during startup into prebiased output	nt Sinking current from external voltage source equal to $V_{OUT} - 0.6V$ and connected to the output via 1 Ω resistor. C _{OUT} =220µF, Aluminum		400	500	mA	
Backdrive Output Current in OFF state	Converter disabled		0	5	mA	
Enable to Output Turn-ON Time	nable to Output Turn-ON Time V _{OUT} = 0.9*V _{OUT_NOM}		15		ms	
Output Enable ON/OFF Negative Enable Converter ON Converter OFF Positive Enable Converter ON Converter OFF		-0.5 2.4 2.4 -0.5		0.8 20 20 0.8	VDC VDC VDC VDC	
Output Voltage Overshoot @ Startup		0.0	0	2	%Vo	
Auto-Restart Period	(all protection features)		100		ms	

* Note: 10% trim-up/remote sense limited to 20 - 60 Vin range





CHARACTERISTIC CURVES:

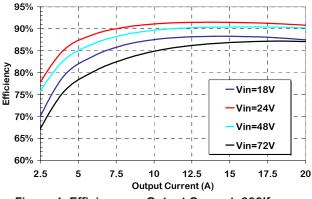


Figure 1. Efficiency vs Output Current, 300lfm airflow, 25 $^{\circ}$ C ambient.

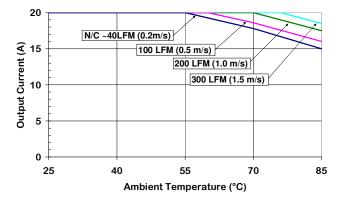


Figure 3. Output Current Derating vs Ambient Temperature & Airflow (air flowing from pin 3 to pin 1, Vin = 48 V, without baseplate)

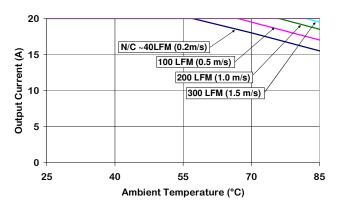


Figure 5. Output Current Derating vs Ambient Temperature & Airflow (air flowing from pin 3 to pin 1, Vin = 36 V, without baseplate)

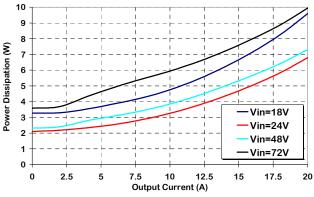


Figure 2. Power Dissipation vs. Load Current, 300lfm airflow, 25 ℃ ambient.

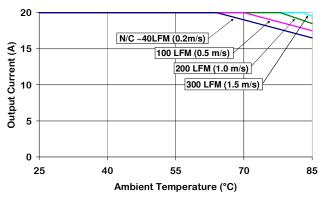


Figure 4. Output Current Derating vs Ambient Temperature & Airflow (air flowing from pin 3 to pin 1, Vin = 24 V, without baseplate)

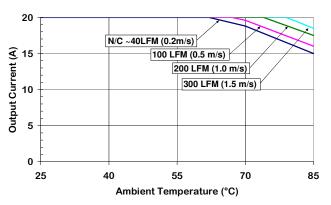


Figure 6. Output Current Derating vs Ambient Temperature & Airflow (air flowing from pin 3 to pin 1, Vin = 24 - 48 V, <u>with</u> baseplate)





CHARACTERISTIC WAVEFORMS:

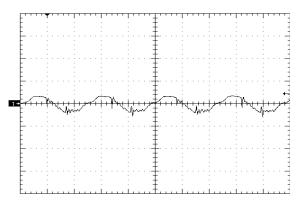


Figure 7. Output Voltage Ripple (20mV/div), time scale – 1uS/div. Vin=Vin_nom, full resistive

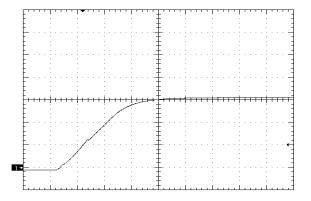


Figure 9. Startup Waveform via Enable Pin, time scale 4mS/div. Vin=Vin_nom, full resistive load (negative enable.)

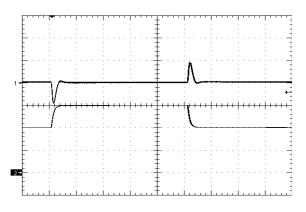


Figure 11. Load Transient Response (100mV/div), di/dt=0.1A/uS, 50% - 75% - 50% of full load, time scale: 200uS/div.

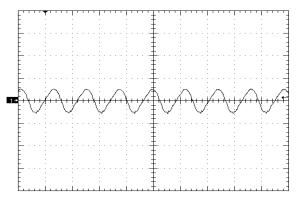


Figure 8. Input Reflected Ripple Current (10mA/div) time scale - 2uS/div. Vin=Vin_nom, full resistive

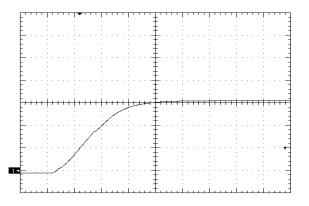


Figure 10. Startup Waveform via Enable Pin, time scale 4mS/div. Vin=Vin_nom, full resistive load + 10000uF (negative enable.)

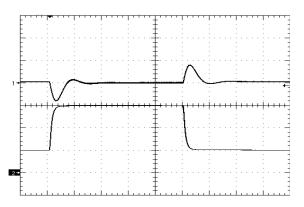


Figure 12. Load Transient Response (100mV/div), di/dt=0.5 A/uS, 25% - 75% - 25% of full load, 2000uF low ESR Oscon, time scale: 200uS/div.

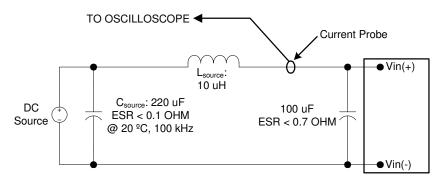




Application Notes

Input Voltage Reflected Ripple Measurement

• INPUT REFLECTED RIPPLE TEST SETUP:

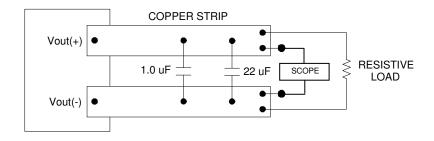


Note: Measure input reflected-ripple current with a simulated source inductance (Ltest) of 10 uH. Capacitor C_8 offsets possible source impedance.

Figure 13. Input Reflected-ripple Current Test Setup.

Output Voltage Ripple Measurement

• OUTPUT RIPPLE TEST SETUP:



Note: Use a 1 μ F X7R ceramic capacitor and a 22 μ F ceramic capacitor. Scope measurement should be made using a BNC socket. Position the load 3 in. [76mm] from module.

Figure 14. Peak-to-Peak Output Noise Measurement Test Setup.



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OUTPUT VOLTAGE TRIM

Output voltage adjustment is accomplished by connecting an external resistor between the Trim Pin and either the +Vout (or +Sense) or -Vout (or -Sense) Pins.

TRIM UP EQUATION:

$$\operatorname{Rtrim_up} = \left[\frac{5.1 \times \operatorname{Vo_nom} \times (100 + \Delta\%)}{1.225 \times \Delta\%} - \frac{510}{\Delta\%} - 10.2\right] \times k\Omega$$

Where Rtrim_up is the resistance value in k-ohms and Δ % is the percent change in the output voltage.

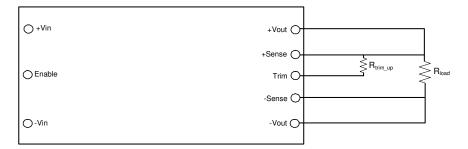


Figure 15. Trim UP circuit configuration

TRIM-DOWN EQUATION:

Rtrim_down =
$$\left(\frac{510}{\Delta\%} - 10.2\right) \times k\Omega$$

Where Rtrim_down is the resistance value in k ohms and $\Delta\%$ is the percent change in the output voltage.

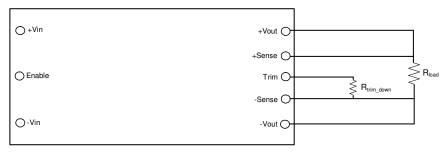


Figure 16. Trim DOWN circuit configuration



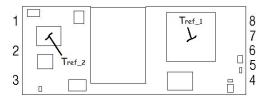
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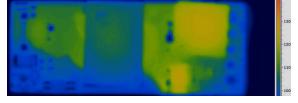


Thermal Derating

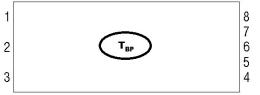
- It is preferable that the DC-DC module have an unobstructed flow of air across it for best thermal performance. Components taller than ~ 2mm in front of the module can deflect airflow and possibly create hotspots.
- Significant cooling is achieved through conductive flow from the modules I/O pins to the host PCB. Sufficiently large traces connecting the dc-dc converter to the source and load will help ensure thermal derating performance will meet or exceed the derating curves published in this datasheet.
- Derating curves are generated near sea level altitude; appropriate reduction in thermal derating must be included for elevations above ~1000m. This is especially important for applications using forced airflow cooling.
- If the module is expected to be operated near the load limits defined in the derating curves, insystem verification of module derating performance should be performed to ensure long-term system reliability. Peak temperatures are to be measured using infrared thermography or by gluing a fine gauge (AWG #40) thermocouple at the T_{ref} location(s) shown below. T_{ref_2} should be monitored for input voltages below 30 Vin, T_{ref_1} for input voltages > 30 Vin. Temperatures at the specified location(s) are not to exceed 123°C in order to maintain converter reliability. For baseplate models, T_{BP} should not exceed 115°C.



Open Frame Measurement Points



Thermal Image of module @ 48Vin, 200LFM & 70C



Baseplate Measurement Point

Input Undervoltage Lockout

• The converter is disabled until the input voltage has exceeded the UVLO turn-on threshold. Once the input voltage exceeds this level (see Input Under-Voltage Lock-out in Electrical Specifications table) the module will commence soft-start. Hysteresis of 2-3 volts minimizes the likelihood of pulling the input voltage below the turn-off threshold during startup which could create an undesirable on/off cycling condition. The converter will continue to operate until the input voltage subsequently falls below the UVLO turn-off threshold.



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Enable Pin Function

- The module has a remote enable function that allows it to be turned on or off remotely. The Enable pin is referenced to the negative input pin (-Vin) of the converter. Modules can be ordered with either negative or positive enable.
- The negative enable option the module will not turn on unless the enable pin is connected to Vin. The positive enable option allows the converter to turn on as soon as voltage sufficient to exceed the UVLO of the converter has been applied to the input terminals. In this case the module is turned off by connecting the Enable pin to –Vin. On/off thresholds are located in the Electrical Specifications table.

Output Overvoltage Protection

• The module has an independent feedback loop that will disable the output of the converter if a voltage greater than about 125% of the nominal set point is detected. When this threshold is reached, the converter will shut down and remain off for the amount of time specified by the Auto-Restart Period. The converter will attempt a restart once this period of time has elapsed.

Output Overtemperature Protection

• To provide protection under certain fault conditions, the unit is equipped with a thermal shutdown circuit. The unit will shutdown if the average PCB temperature exceeds approx. 135°C, but the thermal shutdown is <u>not</u> intended as a guarantee that the unit will survive temperatures beyond its rating. The module will automatically restart once it has cooled below the shutdown temperature minus hysteresis (typically 20 deg C.)

SMT Version Layout Considerations (if applicable)

- Copper traces with sufficient cross-section must be provided for all output & input pins. SMT pads tied to internal power/ground planes must have multiple vias around each SMT pad to couple expected current loads from module pins into internal traces/planes. One 0.024" (0.6mm) diameter via for each 4A of expected source or load current must be provided as close to the termination as possible, preferably in the direction of current flow from SMT pad to load. Vias must be at least 0.024" (0.6 mm) away from the SMT pad to prevent solder from flowing into the vias.
- SMT pads on the host card are to be 0.080" (2.03 mm) diameter. Solder paste screen opening should be 0.075" (1.9 mm) diameter and the screen should be 0.006" (0.15 mm) thick (other thicknesses are possible; 0.006" provides a good compromise between solder volume and coplanarity compensation.)

Paralleling Converters

• Modules may be paralleled but it is recommended that the total power draw not exceed the output power rating of a single module. External sharing controllers are recommended for reliability and to ensure equal distribution of the load to the converters.





EMC Compliance

To meet Class B compliance for EN55032 (CISPR 32) or FCC part 15 sub part j, the following input filter is required:

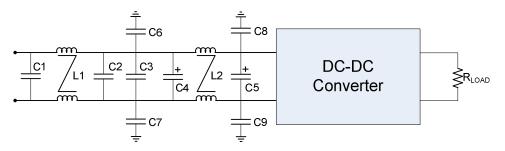


Figure 17. EMI Filter

L1, L2 =	0.77 mH Common Mode Inductor (Pulse P0422)				
C1, C2, C3 =	2.2uF ceramic				
C4 =	Not used				
C5 =	100uF electrolytic				
C6, C7 =	8.2nF (@2kV if output is ref. to gnd.)				
C8, C9 =	8.2nF (@2kV if output is ref. to gnd.)				

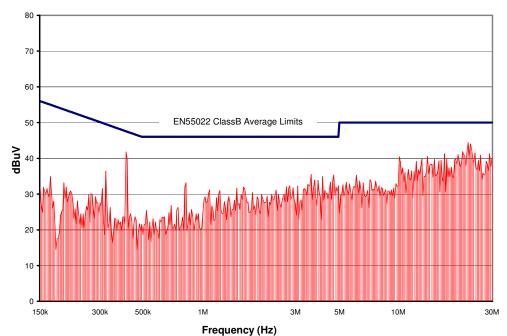


Figure 18. CPE20F36 Conducted Emissions using above specified input filter. Vin = 48V, Full Resistive Load



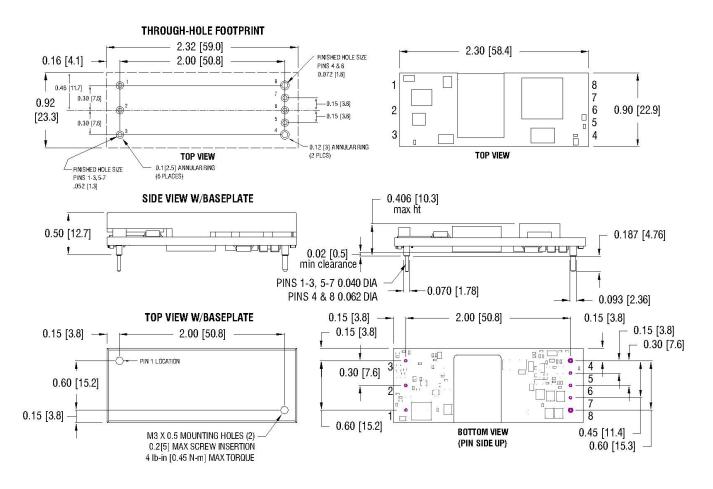
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MODULE PIN ASSIGNMENT:

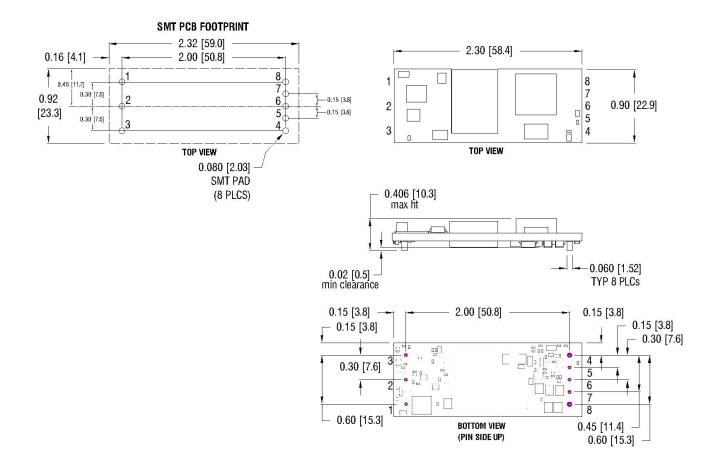
PIN #	DESIGNATION	NOTES
1	V _{IN} (+)	1) All dimensions in inches [mm]
2	On/Off	Tolerances: .xx ± 0.02 [.x ± .5] .xxx ± 0.010 [.xx ± .25]
3	V _{IN} (-)	2) Input, on/off control and sense/trim pins are Ø 0.040" [1.02]
4	V _{оит} (-)	with Ø 0.070" [1.77] standoff shoulders. 3) Output pins are Ø 1.57 mm (0.062") with Ø 0.093" [2.36]
5	Sense (-)	shoulders (note, shoulder sits .008" above mounting surface)
6	Trim	4) All pins are gold plated with nickel under plating. 5) Weight: 22.4 g (0.79 oz.) open frame
7	Sense (+)	39.1 g (1.38 oz.) baseplate model
8	V _{OUT} (+)	6) Workmanship: Meet or exceeds IPC-A-610 Class II

MECHANICAL OUTLINE – THROUGH-HOLE:





MECHANICAL OUTLINE – SMT:





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ORDERING INFORMATION:							
Product Identifier	Output Current	Output Voltage	Input Voltage	Enable logic option	SMT or Baseplate*		
CPE	20	F	36	N or P	S or B		
"Cool Power Eighth"	20A	3V3	18 – 72V	N = Negative P = Positive	S = Surface Mount B = Baseplate Option		

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